



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-04-26
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
CLT03-2Q3	8S8C*U1P3AS1	A	Z6HA	2016-04-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	20.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFF	4-2-0.9	16	No lead	
Comment	Package: DFN.40.20.10-050-16L-E			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	858C*U1P3A51					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	Other inorganic materials	1.150	mg	supplier	die	Silicon (Si)	7440-21-3		1.092	mg	949565	54600
			mg	supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	10435	600
			mg	supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	1739	100
			mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.032	mg	27826	1600
			mg	supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.012	mg	10435	600
Leadframe	Copper and its alloy	5.276	mg	supplier	Alloy	Copper (Cu)	7440-50-8		5.118	mg	970053	255900
			mg	supplier	Alloy	Iron (Fe)	7439-89-6		0.111	mg	21039	5550
			mg	supplier	Alloy	Phosphorus (P)	12185-10-3		0.004	mg	758	200
			mg	supplier	Alloy	Zinc (Zn)	7440-66-6		0.008	mg	1516	400
			mg	supplier	Alloy	Silver (Ag)	7440-22-4		0.035	mg	6634	1750
Die attach	Other organic materials	0.099	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.065	mg	656566	3250
			mg	supplier	glue or tape	methylene diacrylate	42594-17-2		0.024	mg	242424	1200
			mg	supplier	glue or tape	Dicyclopentenylmethacrylate	68586-19-6		0.003	mg	30303	150
			mg	supplier	glue or tape	Polymer of Polybutadiene + Anhydride	Proprietary		0.003	mg	30303	150
			mg	supplier	glue or tape	Bis(alpha,dimethylbenzyl) peroxide	80-43-3		0.004	mg	40404	200
Bonding wire	Other inorganic materials	0.091	mg	supplier	Bonding Wire	Gold (Au)	7440-57-5		0.091	mg	1000000	4550
Encapsulation	Other organic materials	13.384	mg	supplier	molding compound	Silica, vitreous	60676-86-0		12.393	mg	925956	619650
			mg	supplier	molding compound	epoxy resin	85954-11-6		0.535	mg	39973	26750
			mg	supplier	molding compound	phenol resin	26834-02-6		0.402	mg	30036	20100
			mg	supplier	molding compound	carbon black	1333-86-4		0.054	mg	4035	2700